



Title of Change:	Backside Laminate for NB3RL02FCT2G, WLCSP-8 Package		
Effective date:	30 October 2015		
Contact information:	Contact your local ON Semiconductor Sales Office or <jonathan.bass@onsemi.com>		
Type of notification:	ON Semiconductor will consider this change accepted.		
Change category:	☒ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☐ Other _____		
Change Sub-Category(s):			
☐ Manufacturing Site Change/Addition ☐ Material Change ☒ Datasheet/Product Doc change		☐ Shipping/Packaging/Marking	
☒ Manufacturing Process Change ☐ Product specific change		☐ Other: _____	
Sites Affected:			
☐ All site(s) ☐ not applicable ☐ ON Semiconductor site(s) :		☒ External Foundry/Subcon site(s) Flip Chip US	
Description and Purpose:			
Adding backside wafer laminate to provide additional die protection and enhance marking quality for WLCSP-8 bumped die.			
<u>Old</u> No Backside Laminate  <u>New</u> With Backside Laminate 			
List of affected Standard Parts:			
NB3RL02FCT2G			